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# Attività 2024 Richieste 2025

# ALICE 3-RICH project

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Giacomo Volpe (University & INFN, Bari) On behalf of the ALICE 3 RICH WG

# Italian participating institutes



In collaboration with LNGS-NOA for the packging and with FBK for the SiPM R&D

### ALICE Salerno group joined to the project



#### **Testing SiPMs for ePIC dRICH Cosmic ray telescope**







**NEMES Lab (I)**: **prototipazione e produzione, su piccola scala, di schede elettroniche multistrato**



Prototipi realizzati negli ultimi mesi

#### **Reaching low temperature with liquid N**



# ALICE 3 - RICH



Extend electron and charged hadron ID at momenta higher than the TOF range, e.g in the barrel:  $e/\pi$  : 0.5 - 2 GeV/c  $\pi$ /K : 2.0 - 10.0 GeV/c  $K/p : 4.0 - 16.0$  GeV/c

Barrel RICH: aerogel Cherenkov radiator (2cm, n=1.03) + 20 cm expansion gap + SiPM photon detector Forward RICH: idem, but aerogel n = 1.006

**Results from "fast" parametric simulation, assuming a Cherenkov angle resolution at saturation of 1.5 mrad and a TOF time resolution of 20 ps**



### ALICE 3 - RICH





z[m]



# ALICE 3 - RICH



The Cherenkov radiator comprises hydrophobic aerogel tiles (15  $\times$  15  $\times$  2 cm<sup>3</sup> refractive index *n* = 1.03)

The photodetection layer, positioned 20 cm from the radiator, relies purely on proximity focusing.

Each photon detector module covers an area of approximately 20  $\times$  20 cm<sup>2</sup>, featuring an optimized SiPM pixel size of  $2 \times 2$  mm<sup>2</sup>, 1x1 cm<sup>2</sup> die.



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### Simulation studies (by N. Nicassio): assumptions



### Radiator

- Aerogel,  $n = 1.03$
- Tickness: 2 cm
- Transmittance and n vs wavelenght from Aerogel Factory Co., Ltd. (Chiba, Japan) data

### Cylindrical projective geometry

- All aerogel tiles oriented toward nominal interacion point
- Full coverage to charged particles without ovelaps
- Trapeizoidal tile profile to maximize the acceptance

### Photon sensor

- Silicon Photon Multiplier (SiPM)
- Pixel size: 2x2 mm2
- $PDE \cong 40 \%$  at 450 nm
- Intrinsic single SiPM time resolution: 50 ps
- DCR: 50 kHz/mm2

24 sectors in z 36 modules in  $r\phi$  for each sector



# Simulation studies (by N. Nicassio): PID purity in p-p and Pb-Pb



### **Angle reconstruction**

- Based on Hough Transform method (HTM)
- Timing cut on hit-track matching
- HTM N<sub>ph,min</sub> cut on clustered hits

### **Particle identification**

- Bayesian approach + probability cut **Background**
- Photons emitted by different tracks
- Aerogel Rayleigh scattered photons
- SiPM dark count hits (in DAQ gate)

#### **Photodetector hit map of Pb-Pb event**





# Simulation studies (by N. Nicassio): Machine learning vs HTM

### **Dataset**

- 5k Pb-Pb ( $b < 3.5$  fm),  $B = 2T$
- $\approx$  20.0 M charged tracks at bRICH
- Composition:  $\pi^{\pm}$ ,  $K^{\pm}$ ,  $p^{\pm}$ ,  $e^{\pm}$ ,  $\mu^{\pm}$

### **ML vs HTM-based PID**

- Overall better effciency\*purity achieved using ML w.r.t. HTM
	- Note: Efficiency limits in HTM due boundary effects: need for refined  $N_{HTM}$  conditions
	- The effect is automatically learned by my ML algorithm
- Better  $e^{\pm}$  &  $\mu^{\pm}$  purities with ML
- ML worsening above ≈ 10 GeV/*c*
	- Limited statistics of high- $p$ particles in training dataset







### Photon detector

#### **SiPM specifications:**

pixel size = 2x2 mm<sup>2</sup>, die (SiPM array) size ~ 1x1 cm<sup>2</sup>, PDE > 40% at 450 nm, DCR < 50 kHz/mm<sup>2</sup>, radiation hardness: NIEL  $\sim 10^{12}$  1 MeV neg/cm<sup>2</sup>, time resolution < 100ps, packaging fill factor > 90% (TSV interconnection)

- Explore custom solutions for 2.5D configuration in CMOS Imaging Sensor technology (partnership with FBK)
- MIP detection by thin radiator window for TOF
	- Anti-reflecting coating
- FEE ASIC
- Module concept and cooling integration (cool down up to -30/-40 °C to reduce the DCR).



### SiPM Array

PCB Interposer with embedded CO2 cooling and annealing

### The barrel RICH challenges – Radiation Load





#### Last update: April 2023



#### **Radiation load for Run 5+6 in pp collisions**

WORK



#### **Radiation load for Run 5+6 in Pb-Pb collisions**



For the Barrel RICH: NIEL  $\sim$  8.4 x 10<sup>11</sup> 1 MeV n<sub>eq</sub>/cm<sup>2</sup> (even worse with ECal,  $\sim$ 10<sup>13</sup>)

**65% running** 

WORK

The barrel RICH challenges – Radiation Load

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- High radiation load expected in the barrel (**NIEL ~ 8.4 x 10<sup>11</sup> 1 MeV neq/cm<sup>2</sup>)**  $\rightarrow$  SiPM DCR increases to not tollerable values ( $> 1$  MHz/mm<sup>2</sup>)
	- Improve SiPM radiation hardness
	- Development of cooling/annealing strategy



# Cooling option

### *Dual-phase CO2 cooling - A good choice for HEP applications*

- advantages of dual-phase  $CO<sub>2</sub>$  cooling for HEP applications:
	- **large latent heat transfer** due to the phase change energy for the transition of liquid to gas
	- operation with **low mass flow** of the coolant is possible
	- low mass flow as well as a low liquid viscosity results in a low pressure drop along cooling pipe
		- **a low pressure drop allows the use of small pipe diameters or technical solutions like micro-**
	- **channel cooling, which allows new detector design concepts**
	- high **heat transfer capability** (typical ~8000 W/Km) is possible despite small pipe diameters
	- practical **temperature range** of −40°C to 25 °C for detector application
	- CO2 is a **natural**, non-toxic, non-flammable, radiation resistant and non-magnetic gas

#### **Micro-channel cooling on Si - A silicon-embedded technology**

- micro-channel cooling in Si is a favorable technology
	- optimized thermal contact with heat sources
	- heavily simplified assemblies
	- $\cdot$  reduction of material
	- **efficient for cooling "chip-like" heat densities**
- basic technological process: deep RIE + (anodic, eutectic, fusion) wafer bonding
- further integrations also possible!
	- example: metal Re-Distribution Layers (RDL) (*M. Ullán et al. (HSTD13, 2023)*)





Hybrid pixel detector & micro-channel cooling plate

Monolithic CMOS detector

**Monolithic CMOS detector** with integrated micro-channels

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### ASIC FEE development



ALCOR (A Low Power Chip for Optical sensors Readout) is a ASIC developed to readout silicon photomultipliers at low temperature. The chip is designed in a 110 nm CMOS technology

Developed by INFN-Torino for SiPM sensors used in the dRICH detector of the ePIC experiment at EIC.

Current plan for the RICH FEE ASIC

- Use ALCOR chip with modularity optimized for the RICH
- Already started a collaboration between INFN Bari, INFN Torino and INAOE (Mexico)
- If ALCOR TDC is suitable also for TOF/RICH purpose only further minor modifications will be needed
- ePIC Run for 64 channel ASIC foreseen beginning 2025



mm  $\infty$ ဖ



**8x8 pixel matrix ASIC ePIC version (64 channels)**

#### $5 \text{ mm}$

### FEE ASIC: simulation results





Dead time effects of ALCOR TDCs not an issue provided to keep the SiPM DCR below 2 MHz/mm2

If a reset is applied to the TDCs from 1 ns to tens of ns before signal arrival, significant efficiency loss mitigation is achieved even with very high DCR

Using a proper time gate for the reset of TDCs is possible to keep excellent efficiency not only in LeadingEdge mode, but also in ToT/SlewRate mode

15 The ultimate efficiency limits vs DCR set by the recovery time of the SiPM  $\rightarrow$ Possible improvements by including signal shaping by the electronics

### FEE ASIC: simulation results



### **FE output signal time constants**

### **FE response to many PE signals**



**Next step: Studying pile-up of multiple photons and SiPM DCR bkg at FE level**

### Packaging: NOA facility at LNGS (Gran Sasso, Italy)



#### **The DarkSide-20k experiment at LNGS**

**Dual-phase argon TPC for searching direct evidence of dark matter at the INFN underground laboratory LNGS, foreseen to begin operations in 2026**

**The TPC is equipped with SiPMs for detecting the prompt scintillation light**



SiPMs based on FBK NUV-HD-Cryo Design, RUCE manufactured by LFoundry

- **~21 m2 TPC PDU** (2 optical planes, Top and Bottom of the TPC)
- **~5 m2 Veto PDU** (all around the TPC)
- Total =  $26 \text{ m}^2$  of SiPM
	- **1400 wafers** (200 mm, **268 SiPM per wafer**, 7.9 x 11.7 mm2)
	- SPAD size = 30µm
	- Yield by contract= 80%, **actual is ~95%**
	- Cathode on the backside, anode pads for wire bonding
- Photodetector Module **(PDM) is 5 x 5 cm2** single output
- **PDU 20 x 20 cm2 = 16 PDM** with 4 differential output channels (1 channel = 4 PDMs summed)

17 *needed for the ALICE 3 RICH!!SiPMs surface comparable to that*

### Packaging: NOA facility at LNGS (Gran Sasso, Italy)











*We can benefit from the DarkSide experience!*

*Already in contact with LNGS director and NOA responsible!!*

*The Nuova Officina Assergi: future perspectives beyond DarkSide-20k (https://doi.org/10.22323/1.441.0310)*





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- Agilent Cary 4000 Series UV-Vis Spectrophotometer acquired by Bari INFN unit beginning 2024.
	- Equipped with an integration sphere
- Transparency measurement on aerogel samples already started



### 2023 prototype beam test (PS T10 2-18 October)





### Cherenkov angle and timing



*Beam test results in term of angular resolution and number of detected photo-electron using commercial SiPM and electronic, in agreement with simulation!!*



*Paper in preparation: "A compact and fast SiPM-based RICH detector for the future high-energy physics experiments"*

### LAPPD option for fRICH



Operation beyond **1013 MeV neq/cm2** leads to SiPM DCR increase above tens of MHz/mm2

- SiPM-based single photon detection not trivial even accounting cooling + annealing The expected radiation load is not an issue for vacuum-based devices like MCPs and LAPPDs
- Excellent time resolution, low DCR and high radiation hardness make them ideal for the fRICH



*Expression of interest from the Yale University group!* 



### 2024 beam test







#### **New PS beam test forseeen for Oct 24!**

Upgrading the set-up with

- SiPM array with 2 mm of pitch  $\rightarrow$  Target sensor for ALICE 3 RICH
- Timing measurement:
	- New custom front-end boards based on Radioroc/Weeroc and picoTDC/CERN
		- The first version is under test
	- Read-out and DAQ with Mosaic boards
- Position measurement still based on the Petiroc 2A boards
- All the boards with common clock and trigger signals Prototype still based on on-the-shelf components
- Test aerogel focusing configuration







# RICH 2025 plans



- Aerogel Characterization (ePIC synergy)
	- Setup for measuring the aerogel refractive index will be implemented, enabling comprehensive optical characterization of the Cherenkov radiator.



- Setup of the refractive index measurement shown in [2].
- Study of the prototype interposer and cooling system
- **Milestone: ottimizzazione configurazione interposer con annesso sistema di cooling a microcanali**
- Test new prototype at CERN-PS
	- Position measurement: new FEE/RO to improve single photon detection efficiency
	- Increase photon sensor acceptance (25 modules, 2.5 k€ each)

### RICH 2025 plans

- RUN ASIC ALCOR
	- One wafer of ALCOR v3 from the ePIC RUN for testing purpose
	- Packaging studies for the ALICE RICH configuration
- RICH module mock-up construction for installation test



6.8 mm



#### **Drawing realized by INFN Bari CAD service**

 $5<sub>mm</sub>$ 

### **ECFA DRD4 activities**

*DRD4 WP 4.4.1: Coupling of a thin Cherenkov radiator to SIPMs, for TOF of charged particles DRD4 WP 4.4.2: SiPM array, with mm-scale pixelization, suitable for use in TOF prototypes*



### **ECFA DRD4 activities**



### *DRD4 WP 4.4.2*

27 Realization of fast electronic boards for timing measurements with TDC FE integrated as WEEROC/OMEGA and/or FastIC+

# Budget request







### Sinergie

#### Sigla in gruppo 5 **ASPIDES: A CMOS SPAD and Digital SiPM Platform for High Energy Physics (ASPIDES)**

The goal of this research activity is the development of a technology platform for the design, production and commissioning of dSiPMs, detectors with single-photon sensitivity and embedded functionalities. The activity will target applications to light detection for dual-readout calorimetry at future leptonic collider experiments, RICH and neutrino experiments.

In the research activity, the collaboration will pursue the development of a planar detector in a standard CMOS technology, naturally lending itself to the design of a monolithic sensor, where the front-end electronics and the sensitive element lie in the same substrate.

Backup

Measurements performed with a Perkin Elmer spectrometer: integrating sphere and two different light sourc $\phi$ cover the range 250 - 800 nm





Each tile was placed into a holder  $(10x10 cm<sup>2</sup>)$  and mounted onto a metal ridge sliding perpendicular to the beam to explore different positions of the samples





$$
T(\lambda) = e^{-\frac{t}{\Lambda_{transm}}} = e^{-t\left(\frac{1}{A_A} + \frac{1}{A_S}\right)} = A \cdot e^{-\frac{B t}{\lambda^8}} \cdot e^{-\frac{C t}{\lambda^4}}
$$



$$
e^{-\sqrt{A_S}t} = e^{-\frac{\lambda^4}{\lambda^4}}
$$

$$
A_{scat} = \frac{\lambda^4}{C}
$$

**ABSORPTION LENGTH:**  
\n
$$
e^{-\left(\frac{t}{A_A}\right)} = A \cdot e^{-\frac{B t}{\lambda^8}}
$$
\n
$$
A_{abs} = \frac{\lambda^8 \cdot t}{B t - \lambda^8 \cdot \ln(A)}
$$



SMALL IMPACT OF THE ABSORPTION ON THE TRANSMISSION LENGTH

Transmittance fitted by *Hunt formula* [NIM A 440 (2000) 338-347]

$$
T(\lambda) = e^{-\frac{t}{A_{transm}}} = e^{-t\left(\frac{1}{A_A} + \frac{1}{A_S}\right)} = A \cdot e^{-\frac{C t}{\lambda^4}}
$$









Transmittance fitted by **Hunt basic**:

$$
T(\lambda) = e^{-\frac{t}{A_{transm}}} = e^{-t\left(\frac{1}{A_A} + \frac{1}{A_S}\right)} = A \cdot e^{-\frac{C t}{\lambda^4}}
$$





Transmittance fitted by **Hunt extended**:

$$
T(\lambda) = e^{-\frac{t}{A_{transm}}} = e^{-t\left(\frac{1}{A_A} + \frac{1}{A_S}\right)} = A \cdot e^{-\frac{B t}{\lambda^8}} \cdot e^{-\frac{C t}{\lambda^4}}
$$





**<T> = average of the transmittance values at the different points on the tile #1 (n = 1.03)**

The shape of the tile has implications on the transmittance.



#### $n=1.03$



#### $n=1.04$



#### $n=1.05$



### **Thickness and flatness measurement in metrology lab at CERN!**

- Results obtained on a tile of  $n = 1.03$  with the touch probe system (force applied by the probe is 2 gr).
- The measuring system is the LEITZ PMMC with  $\pm$  0.3  $\mu$ m of precision



There is a variation in thickness from the centre to the edges, of the order of 0.4 mm, and a different planarity in the two faces, one 0.7 mm, the other 1.27 mm. In general the tiles have the shape of a dome.

- The manufacturer (Aerogel Factory Ltd, Chiba, JP) stated that it is possible to improve the flatness and the thickness uniformity;
- the planarity can be mapped, to include the defect in the reconstruction of the Cherenkov angle.



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### Simulation studies (by N. Nicassio)

